L Number	Hits	Search Text	DB	Time stamp
-	27	etch\$3 same (interlayer interlevel	USPAT;	2002/03/14 12:23
		intermediate) same (organic teflon	US-PGPUB; EPO; JPO;	
		polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)	DERWENT;	
		"NH.SUD.3" dillilonia)	IBM TDB	
_	2300	etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:02
	2500	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)	IBM_TDB USPAT;	2002/03/14 12:22
-	613	(etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2002/05/14 12.22
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	1
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))		
-	350	(etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 12:22
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel	DERWENT; IBM TDB	
1		intermediate) near dielectric) not (etch\$3	TBR_TBB	
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	005	ammonia))	HCDAT.	2002/03/14 12:23
	925	((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6	USPAT; US-PGPUB;	2002/03/14 12.23
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyary1\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))	HODAM	2002/03/14 12:23
-	289	(((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6	USPAT; US-PGPUB;	2002/03/14 12:23
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyary1\$6   poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
:		interlevel intermediate) and (organic teflon		
:		polyary1\$6 poly\$1para\$1xylene) and (NH3		
		"NH. sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate)		
		same (organic teflon polyary)\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)	1	<u> </u>

		//// halda a /interlance interland	USPAT;	2002/03/14 12:23
-	184	((((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2002/03/14 12:23
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3	12122	
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		polysiparasixyrene/ same (Mis Misabis		
		ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon		
		interlevel intermediate, and (organic terron		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		1
		"NH. sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
	į	intermediate) near dielectric) not (etch\$3		
	1	same (interlayer interlevel intermediate)		
		same (organic teflon polyary1\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
1		ammonia)) and etch\$3 with (NH3 "NH.sub.3"	:	
		ammonia)		0000/00/14 10 04
-	37	(((((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 12:24
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	,
1	1	ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM_TDB	
		intermediate) near insulat\$3) not (etch\$3		
,		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)) ) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
	1	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and (interlayer interlevel		
		intermediate) with (organic teflon		
	i	polyaryl\$6 poly\$1para\$1xylene)		
_	780	(etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:03
		intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
1		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and (NH3 "NH.sub.3" ammonia) same	IBM_TDB	
		(plasma merie RIE dry adj etch\$3)	_	
_	430		USPAT;	2002/03/14 13:04
	150	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	ļ
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
	1	interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
1	1	intermediate) near dielectric) not (etch\$3		
1		same (interlayer interlevel intermediate)		
1				
		same (organic teflon polyaryl\$6   poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
1		polystpalasixyteme) same (Nns "Nn. sub.s"		
		ammonia)))) and (NH3 "NH.sub.3" ammonia)		
1	l	same (plasma merie RIE dry adj etch\$3)		1

212	(((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:05
- 313	intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2002, 00, 22 20110
	poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	•
	ammonia) and (plasma merie RIE dry adj	DERWENT;	
	etch\$3)) and ((interlayer interlevel	IBM TDB	
	intermediate) near insulat\$3) not (etch\$3	1511_155	1
	intermediate) hear insulaces; not (ecches		
	same (interlayer interlevel intermediate)	1	
	same (organic teflon polyaryl\$6		
	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon		
	interlevel intermediate, and (organic terron		ĺ
	polyary1\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE	;	
	dry adj etch\$3)) and ((interlayer interlevel		
	intermediate) near dielectric) not (etch\$3		
	same (interlayer interlevel intermediate)		
	same (interlayer interlevel intermediate)		
	same (organic teflon polyary1\$6   poly\$1para\$1xylene) same (NH3 "NH.sub.3"	1	
	ammonia)))) and (NH3 "NH.sub.3" ammonia)		
	with (plasma merie RIE dry adj etch\$3)		
		USPAT;	2002/03/14 13:05
- 63	(((((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6	US-PGPUB;	2302,03,11 13.03
	poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
	ammonia) and (plasma merie RIE dry adj	DERWENT;	
	etch\$3)) and ((interlayer interlevel	IBM TDB	
	intermediate) near insulat\$3) not (etch\$3	1511_155	
	same (interlayer interlevel intermediate)		
	same (organic teflon polyary1\$6		
	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	ammonia))) ((etch\$3 and (interlayer		
	interlevel intermediate) and (organic teflon		
	polyaryl\$6 poly\$1para\$1xylene) and (NH3		
	"NH.sub.3" ammonia) and (plasma merie RIE		
	dry adj etch\$3)) and ((interlayer interlevel		
	intermediate) near dielectric) not (etch\$3		
	same (interlayer interlevel intermediate)		
	same (organic teflon polyaryl\$6		
	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
	ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
	ammonia)) and ((((etch\$3 and (interlayer		
	interlevel intermediate) and (organic teflon		
	polyaryl\$6 poly\$1para\$1xylene) and (NH3		
	"NH.sub.3" ammonia) and (plasma merie RIE		
	dry adj etch\$3)) and ((interlayer interlevel		
	intermediate) near insulat\$3) not (etch\$3		
	same (interlayer interlevel intermediate)		
	same (organic teflon polyary)\$6		
1	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	ammonia))) ((etch\$3 and (interlayer		
	interlevel intermediate) and (organic teflon		
	polyaryl\$6 poly\$1para\$1xylene) and (NH3		
1	"NH.sub.3" ammonia) and (plasma merie RIE		
	dry adj etch\$3)) and ((interlayer interlevel		
	intermediate) near dielectric) not (etch\$3		
	same (interlayer interlevel intermediate)		
1	same (organic teflon polyaryl\$6		
	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
	ammonia)))) and (NH3 "NH.sub.3" ammonia)		
	with (plasma merie RIE dry adj etch\$3))		

-	43	(((((etch\$3 and (interlayer interlevel	USPAT;	2002/03/14 13:05
		intermediate) and (organic teflon polyary1\$6	US-PGPUB;	
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"	EPO; JPO;	
		ammonia) and (plasma merie RIE dry adj	DERWENT;	
		etch\$3)) and ((interlayer interlevel	IBM TDB	
		intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		
1				
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
	ļ	poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
				,
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
	ŀ	ammonia)) and ((((etch\$3 and (interlayer		
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
	1	intermediate) near insulat\$3) not (etch\$3		
		same (interlayer interlevel intermediate)		İ
		same (organic teflon polyary1\$6		1
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia))) ((etch\$3 and (interlayer	1	
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
		"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		
		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and (NH3 "NH.sub.3" ammonia)		
}		with (plasma merie RIE dry adj etch\$3))) not		
		(((((etch\$3 and (interlayer interlevel		1
		intermediate) and (organic teflon polyaryl\$6		
		intermediate, and torganic cerron poryaryipo		
		poly\$1para\$1xylene) and (NH3 "NH.sub.3"		
		ammonia) and (plasma merie RIE dry adj		1
		etch\$3)) and ((interlayer interlevel		
		intermediate) near insulat\$3) not (etch\$3	1	
ļ l		same (interlayer interlevel intermediate)		
		same (organic teflon polyaryl\$6		
		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		ļ
		ammonia)) ) ((etch\$3 and (interlayer		1
		interlevel intermediate) and (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene) and (NH3		
	1	"NH.sub.3" ammonia) and (plasma merie RIE		
		dry adj etch\$3)) and ((interlayer interlevel		
		intermediate) near dielectric) not (etch\$3		1
		same (interlayer interlevel intermediate)		
1		same (Interlayer Interlever Intermediate)   same (organic teflon polyaryl\$6	1	
]		same (organic cerron poryaryrso		
ļ		poly\$1para\$1xylene) same (NH3 "NH.sub.3"		
		ammonia)))) and etch\$3 same (NH3 "NH.sub.3"		
		ammonia)) and etch\$3 with (NH3 "NH.sub.3"		
		ammonia)) and (interlayer interlevel		
		intermediate) with (organic teflon		
		polyaryl\$6 poly\$1para\$1xylene))		
_	25		USPAT;	2004/06/27 09:33
		dissolv\$3) near (photoresist resist) with	US-PGPUB;	
1	1	((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
-		(HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT;	
1		O.sub.2"))	IBM TDB	
	<u> </u>	U.SUD. 2   1	1	1

-	64	(strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT;	2004/06/27 08:45
·		dissolv\$3) with (photoresist resist) same	US-PGPUB;	
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2	EPO; JPO; DERWENT;	
			IBM TDB	
	30	O.sub.2")) ((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT;	2004/06/27 08:53
_	39	dissolv\$3) with (photoresist resist) same	US-PGPUB;	2001, 00, 21 00100
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
		(HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT;	
		O.sub.2"))) not ((strip\$4 remov\$3 etch\$3	IBM TDB	
		clean\$3 develop\$3 dissolv\$3) near		
		(photoresist resist) with ((H2SO4 "H.sub.2		
		SO.sub.4" sulfuric) with (HF fluori?e) with		
		(peroxide H2o2 "H.sub.2 O.sub.2")))		
_	38	(("5266157") or ("6352937") or ("6033996")	USPAT;	2004/06/27 08:47
		or ("5384649") or ("5584740") or ("6153484")	US-PGPUB;	
	:	or ("3944421") or ("4883541") or ("5300463")	EPO; JPO;	
		or ("5985125") or ("5824419") or ("5830280")	DERWENT;	
		or ("5250958") or ("6124211") or ("6046115")	IBM_TDB	
		or ("6030879") or ("5776817") or ("5716495")		
	19	or ("5296093")).PN. (("5266157") or ("6352937") or ("6033996")	USPAT	2004/06/27 08:47
-	19	or ("5384649") or ("5584740") or ("6153484")		
		or ("3944421") or ("4883541") or ("5300463")		
		or ("5985125") or ("5824419") or ("5830280")		
		or ("5250958") or ("6124211") or ("6046115")		
		or ("6030879") or ("5776817") or ("5716495")		
		or ("5296093")).PN.		
-	58	(((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3	USPAT;	2004/06/27 09:32
		dissolv\$3) with (photoresist resist) same	US-PGPUB;	
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with	EPO; JPO;	
		(HF fluori?e) with (peroxide H2o2 "H.sub.2	DERWENT;	
		0.sub.2"))) ((("5266157") or ("6352937") or	IBM_TDB	
		("6033996") or ("5384649") or ("5584740") or ("6153484") or ("3944421") or ("4883541") or		
		("5300463") or ("5985125") or ("5824419") or		
		("5830280") or ("5250958") or ("6124211") or		*
		("6046115") or ("6030879") or ("5776817") or		
		("5716495") or ("5296093")).PN.)) not		
		((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3		
		dissolv\$3) near (photoresist resist) with		
		((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with		
		(HF fluori?e) with (peroxide H2o2 "H.sub.2		
		O.sub.2")))		0004/05/07 00 10
-	0	20040016719.URPN.	USPAT	2004/06/27 08:49
-	10		USPAT;	2004/06/27 09:32
		US-5326490-\$ or US-5185154-\$ or US-4883541-\$	DERWENT	
		or US-4585515-\$ or US-5804744-\$ or US-5863828-\$ or US-6352937-\$).did. or		
		(JP-05013920-\$).did.		
	6	1 1	USPAT;	2004/06/27 09:33
-		US-6225424-\$ or US-6417510-\$ or	US-PGPUB	
		US-6509686-\$).did. or		
		(US-20010037979-\$).did.		
_	16	((US-5996424-\$ or US-5266157-\$ or	USPAT;	2004/06/27 09:33
		US-5326490-\$ or US-5185154-\$ or US-4883541-\$	US-PGPUB;	
		or US-4585515-\$ or US-5804744-\$ or	EPO; JPO;	
		US-5863828-\$ or US-6352937-\$).did. or	DERWENT;	
		(JP-05013920-\$).did.) ((US-5605602-\$ or	IBM_TDB	
		US-5589077-\$ or US-6225424-\$ or US-6417510-\$		
		or US-6509686-\$).did. or		
		(US-20010037979-\$).did.)	HEDATE	2004/06/27 19:03
-	4		USPAT	2004/00/2/ 19:03
	0	or ("5895563")).PN. ("0618612").PN.	EPO	2004/06/27 19:03
-	2	"618612" "346668"	EPO	2004/06/27 19:03
	1	1 010011 01000	1	